

# **Typical Applications**

- Communication Systems
- Test Equipment

#### **Features**

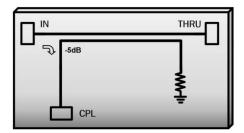
• Frequency Range: 6.0 – 12.0 GHz

Coupling: 5dB ± 0.5

50Ω Matched RF Ports

Low loss, hard Alumina substrate, Gold Wire bondable

• Substrate Size: 4.188 x 1.450 x 0.254 mm





## **Electrical Specifications (TA = +25°C)**

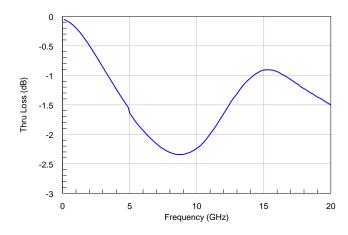
Parameter	Units	Minimum	Typical	Maximum
Frequency	GHz	6.2		11.3
Thru Loss	dB			2.4
Coupling	dB		5.0	
Coupling Flatness	dB		± 0.5	
Return Loss (IN)	dB	13	15	
Return Loss (THRU)	dB	12	15	
Return Loss (CPL)	dB	13	15	
Package Type			Substrate	



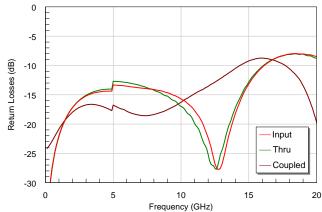


# **Performance Graphs**

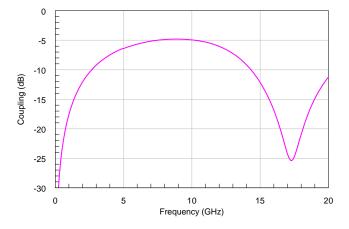
### **Thru Loss**



### **Return Losses**

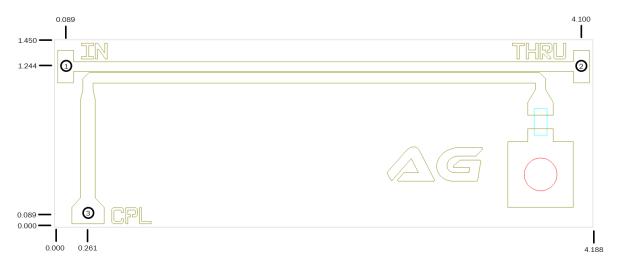


# **Coupling**





# **Outline Drawing (dimensions in mm)**



# **Pad Descriptions**

Pad	Function	Pad Size	Description
1	IN	125x250μm	DC coupled 50Ω Matched
2	THRU	125x250μm	DC coupled 50Ω Matched
3	CPL	250x125μm	AC coupled 50Ω Matched
Die Bottom	GND	Backside	Epoxy/Solder to Baseplate

<sup>\*</sup>See Assembly Diagram

# **Absolute Maximum Ratings**

Parameter	Rating	
Storage Temperature	-65 to 150°C	
Operating Temperature	-55 to 85°C	



# **Assembly Diagram**



## **Assembly Notes:**

- 1. TFN Thickness is 254µm Polished 99.6% Alumina
- 2. Backside and Bondpad metallization: 2.5µm gold
- 3. Silver Epoxy or AuSn Eutectic attach MMIC

# **Die Packaging Information**

GP-4 (Gel-Pak)